



TECHNICAL REPORT



**Environmental testing –
Part 3-82: Supporting documentation and guidance – Confirmation of the
performance of whisker test method**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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ENVIRONMENTAL TESTING –

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IEC TR 60068-3-82 has been prepared by IEC technical committee 91: Electronics assembly technology. It is a Technical Report.

The text of this Technical Report is based on the following documents:

Draft	Report on voting
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this Technical Report is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 60068 series, published under the general title *Environmental testing*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
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ENVIRONMENTAL TESTING –

Part 3-82: Supporting documentation and guidance – Confirmation of the performance of whisker test method

1 Scope

This part of IEC 60068, which is a Technical Report, provides technical background information on the whisker test methods from IEC 60068-2-82 and guidance on test selection.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-82:2019, *Environmental testing – Part 2-82: Tests – Test XW1: Whisker test methods for components and parts used in electronic assemblies*

IEC 61190-1-1, *Attachment materials for electronic assembly – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 62483, *Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices*

ISO 9454-2:2020, *Soft soldering fluxes – Classification and requirements – Part 2: Performance requirements*